

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

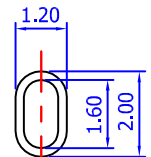
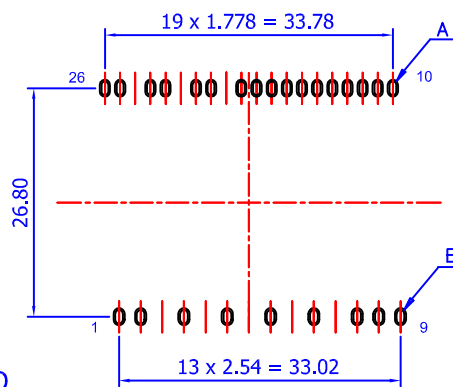
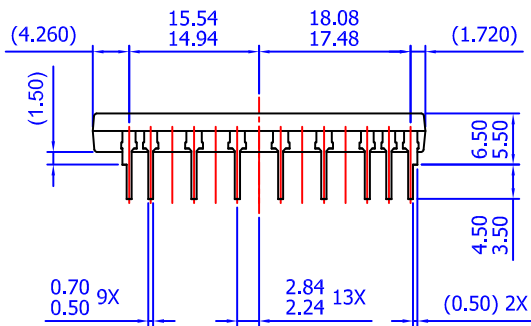
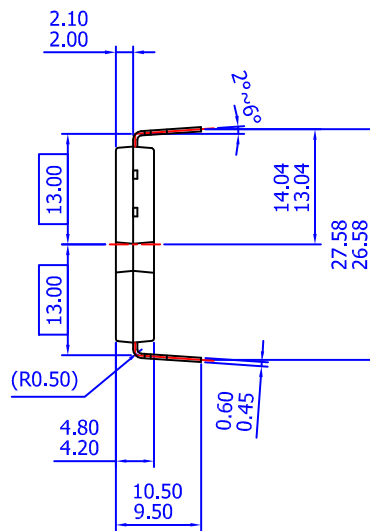
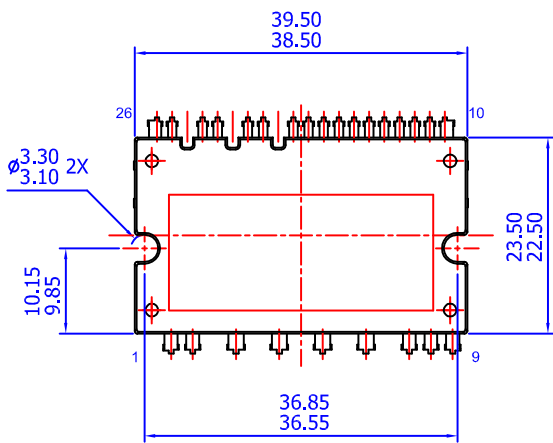
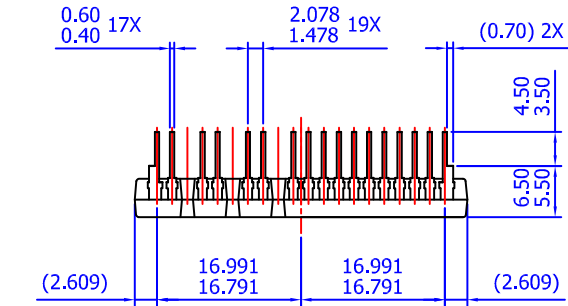
ON Semiconductor®



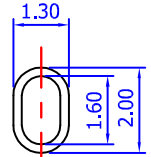
SPMAA-A26 / 26LD, PDD STD, CERAMIC TYPE, STANDARD DUAL FORM

CASE MODFA
ISSUE O

DATE 31 JAN 2017



DETAIL A (SCALE N/A)



DETAIL B (SCALE N/A)

LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPMAA-A26 / 26LD, PDD STD, CERAMIC TYPE, STANDARD DUAL	PAGE 1 OF 2

